

**IN THE CLAIMS:**

1. (Currently Amended) A method of manufacturing a layered silicone composite material comprising the steps of:

applying a second addition-curable organopolysiloxane composition that contains ~~consisting essentially of~~ (A) an organopolysiloxane having an average of at least two silicon-bonded alkenyl groups per molecule, (B) an organopolysiloxane having an average of at least two silicon-bonded hydrogen atoms per molecule, (C) a hydrosilylation catalyst for addition reactions, a second adhesion promoter, and optional additives selected from the group of fillers, addition-reaction inhibitors, dyes, pigments, flame retardants, and solvents onto a first silicone layer that is formed by curing a first addition-curable organopolysiloxane composition containing ~~consisting essentially of~~ (A) an organopolysiloxane having an average of at least two silicon-bonded alkenyl groups per molecule, (B) an organopolysiloxane having an average of at least two silicon-bonded hydrogen atoms per molecule, (C) a hydrosilylation catalyst for addition reactions, a first adhesion promoter, and optional additives selected from the group consisting of fillers, addition-reaction inhibitors, dyes, pigments, flame retardants, and solvents, and where the first silicone layer has a hardness of less than JIS A 50; and

forming a second silicone layer that has a hardness of JIS A 50 or more by curing said second addition-curable organopolysiloxane composition[.];

wherein at least one of the first adhesion promoter and the second adhesion promoter is an organosilicon compound containing, per molecule, at least one silicon-bonded alkenyl group and at least one epoxy group.

2. (Cancelled)
3. (Currently Amended) The method according to Claim ~~[[1]]~~17, where at least one of the first adhesion promoter and the second adhesion promoter ~~is an organosilicon compound containing, per molecule,~~ further contains, per molecule, at least one alkoxy group, at least one alkoxyalkoxy group, or both.
4. (Currently Amended) The method according to Claim 3, where ~~both of at least one of the first adhesion promoter and the second adhesion promoter contains at least one silicon bonded alkenyl group, at least one silicon bonded hydrogen atom, or both~~ further contain, per molecule, at least one alkoxy group, at least one alkoxyalkoxy group, or both.
5. (Currently Amended) The method according to Claim 3, where at least one of the first adhesion promoter and the second adhesion promoter further contains, per molecule, at least one ~~epoxy group~~ silicon-bonded hydrogen atom.
6. (Previously Presented) The method according to Claim 1, where at least one of the first addition-curable organopolysiloxane composition and the second addition-curable organopolysiloxane composition is free of inorganic filler.
7. (Previously Presented) The method according to any of Claim 1, where the layered silicone composite material is an optically transparent material.

8. (Currently Amended) The method according to ~~any of~~ Claim 1, where the layered silicone composite material is ~~at least~~ a part of an optical element.

9-16. (Cancelled)

Please add the following new claims.

17. (New) The method according to Claim 1, where both of the first adhesion promoter and the second adhesion promoter are an organosilicon compound each individually containing, per molecule, at least one silicon-bonded alkenyl group and at least one epoxy group.
18. (New) The method according to Claim 7, where the layered silicone composite material has a light permeability index exceeding 80% at 25°C.